

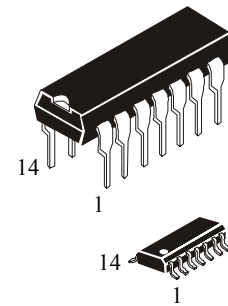
# IL339N

## Quad Comparator

The IL339 consists of four independent voltage comparators with an offset voltage specification as low as 2.0 mV typ. The comparators operate in a wide range of voltages.

Application areas include limit comparators, simple analog to digital converters; pulse, squarewave and time delay generators; wide range VCO; MOS clock timers; multivibrators and high voltage digital logic gates.

- Single or Split Supply Operation
- Low Input Bias Current
- Low Input Offset Current
- Input Common Mode Voltage Range to Gnd
- Low Output Saturation Voltage
- TTL and CMOS Compatible

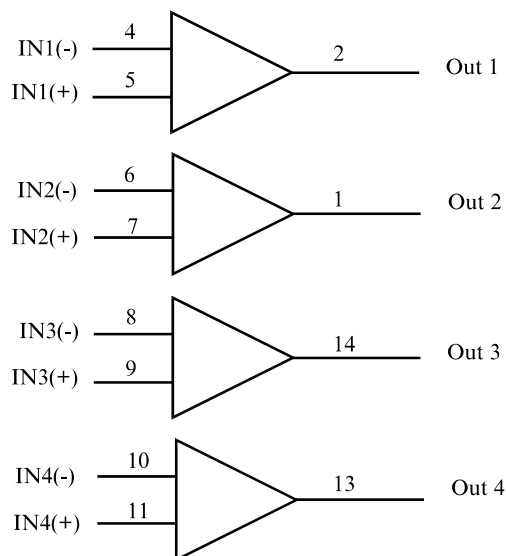


N SUFFIX  
PLASTIC

D SUFFIX  
SOIC

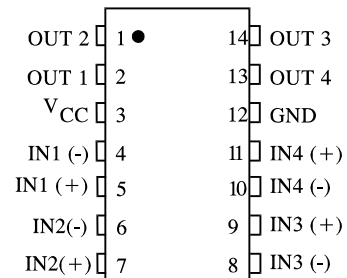
ORDERING INFORMATION	
IL339N	Plastic
IL339D	SOIC
IZ339	Chip

### BLOCK DIAGRAM



PIN 3 =  $V_{CC}$   
PIN 12 = GND

### PIN ASSIGNMENT



## IL339N

### MAXIMUM RATINGS\*

Symbol	Parameter	Value	Unit
$V_{CC}$	Power Supply Voltages Single Supply Split Supplies	36 $\pm 18$	V
$V_{IDR}$	Input Differential Voltage Range	36	V
$V_{ICR}$	Input Common Mode Voltage Range (1)	-0.3 to $V_{CC}$	V
$t_S$	Short-Circuit duration of Output	100	ms
$I_{IN}$	Input Current, per pin (2)	50	mA
$T_J$	Junction Temperature Plastic Package	150	$^{\circ}C$
Tstg	Storage Temperature	-65 to +150	$^{\circ}C$
$T_L$	Lead Temperature, 1mm from Case for 10 Seconds	260	$^{\circ}C$
$P_D$	Power Dissipation $T_A=+25^{\circ}C$ Plastic Package Derate above $25^{\circ}C$	1.0 8.0	W mW/ $^{\circ}C$

\*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

Notes:

1. Split Power Supplies.
2.  $V_{IN} < -0.3V$ .

### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	DC Supply Voltage	$\pm 2.5$ or 5.0	$\pm 15$ or 30	V
$T_A$	Operating Temperature, All Package Types	0	+70	$^{\circ}C$

## IL339N

### DC ELECTRICAL CHARACTERISTICS ( $T_A=0$ to $+70^\circ\text{C}$ )

Symbol	Parameter	Test Conditions	Guaranteed Limit		Unit
			Min	Max	
$V_{IO}$	Input Offset Voltage	$V_0=1.4\text{V}$ $V_{CC}=5.0\text{-}30\text{V}; R_S \leq 100\Omega$ $V_{ICR}=0\text{V} - (V_{CC}-1.5)\text{V}$	-	9.0 5.0*	mV
$I_{IB}$	Input Bias Current	$V_0=1.4\text{V}$ $V_{CC}=5.0\text{-}30\text{V}$ $V_{ICR}=0\text{V} - (V_{CC}-1.5)\text{V}$	-	400 250*	nA
$I_{IO}$	Input Offset Current	$V_0=1.4\text{V}$ $V_{CC}=5.0\text{-}30\text{V}$ $V_{ICR}=0\text{V} - (V_{CC}-1.5)\text{V}$	-	$\pm 150$ $\pm 50^*$	nA
$V_{ICR}$	Input Common Mode Voltage Range	$V_{CC}=5.0\text{-}30\text{V}$	0	$V_{CC}-2.0\text{V}$ $V_{CC}-1.5\text{V}^*$	V
$I_{CC}$	Supply Current	$R_L=\infty, V_{CC}=5.0\text{V}$ $R_L=\infty, V_{CC}=30\text{V}$	- -	2.0* 2.5*	mA
$A_{VOL}$	Voltage Gain	$V_{CC}=15\text{V}, R_L=15\text{K}\Omega$	50*	-	V/mV
$I_{sink}$	Output Sink Current	$V_i(-)=1.0\text{V}, V_i(+)=0\text{V},$ $V_0 \leq 1.5\text{V}, V_{CC}=5.0\text{V}$	6.0*	-	mA
$V_{sat}$	Saturation Voltage	$V_i(-)=1.0\text{V}, V_i(+)=0\text{V},$ $I_{sink} \leq 4.0\text{mA}, V_{CC}=5.0\text{V}$	-	700 400*	mV
$I_{OL}$	Output Leakage Current	$V_i(+)=1.0\text{V}, V_i(-)=0\text{V},$ $V_0=5.0\text{V}$ $V_0=30\text{V}$		1000	nA
$V_{IDR}$	Differential Input Voltage Range	All $V_{IN} \geq 0$		$V_{CC}^*$	V

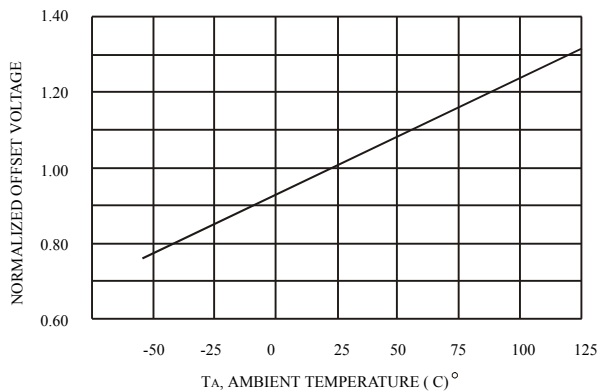
\*  $T_A=+25^\circ\text{C}$

**NOTE:** Guaranteed Limits of DC Electrical Characteristics are given for  $T_A=0, +70^\circ\text{C}$  as the information for chips.

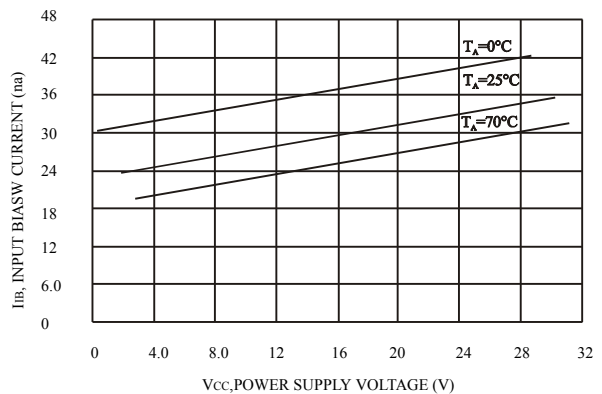
# IL339N

## TYPICAL PERFORMANCE CHARACTERISTICS

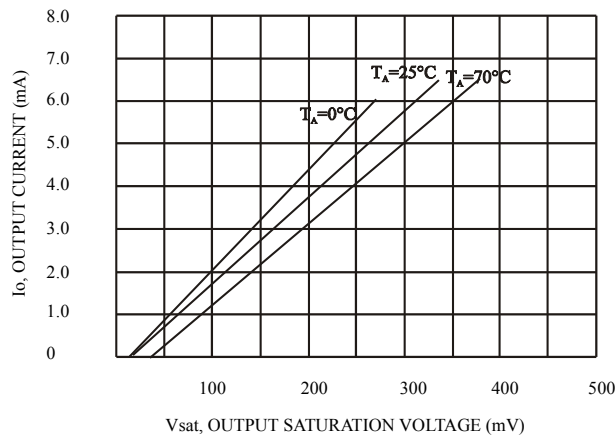
( $V_{CC}=1.5V$ ,  $T_A=+25^{\circ}C$  (each comparator))



**Figure 1. Normalized Input Offset Voltage**



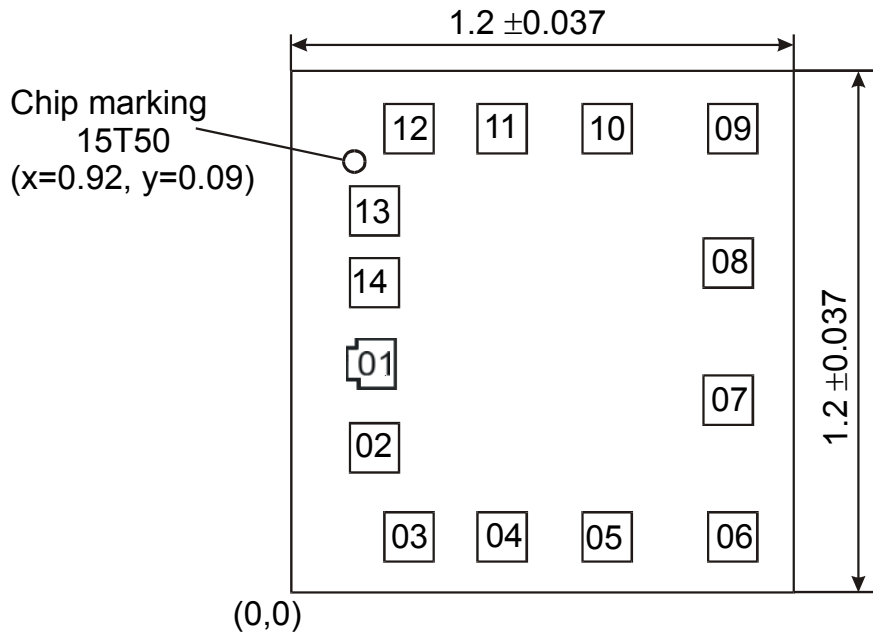
**Figure 2. Input Bias Current**



**Figure 3. Output Sink Current versus Output Saturation Voltage**

## TYPICAL DC ELECTRICAL CHARACTERISTICS ( $T_A=+25^{\circ}C$ )

Symbol	Parameter	Test Conditions	Value	Unit
$t_1$	Large Signal Response Time	$V_{IN}$ =TTL Logic Swing, $V_{ref}=1.4V$ , $V_{CC}=5.0V$ , $R_L=5.1K\Omega$ , $V_{RL}=5.0V$	300	ns
$t_2$	Response Time	$V_{CC}=5.0V$ , $R_L=5.1K\Omega$ , $V_{RL}=5.0V$	1.3	$\mu s$

**CHIP PAD DIAGRAM IZ339**

Pad size 0.110 x 0.110 mm (Pad size is given as per passivation layer)

Thickness of chip 0,46±0,02 mm

**PAD LOCATION**

<i>PAD NO</i>	Symbol	X	Y
01	OUT2	0.100	0.462
02	OUT1	0.100	0.297
03	V <sub>CC</sub>	0.180	0.100
04	IN1 (-)	0.385	0.100
05	IN1 (+)	0.672	0.100
06	IN2 (-)	0.990	0.100
07	IN2 (+)	0.990	0.377
08	IN3 (-)	0.990	0.712
09	IN3 (+)	0.990	0.990
10	IN4 (-)	0.672	0.990
11	IN4 (+)	0.385	0.990
12	GND	0.180	0.990
13	OUT4	0.100	0.793
14	OUT3	0.100	0.625

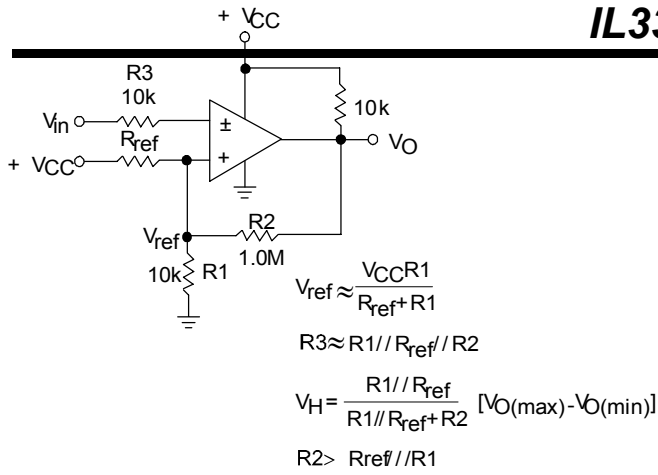


Figure 4. Inverting Comparator with Hysteresis

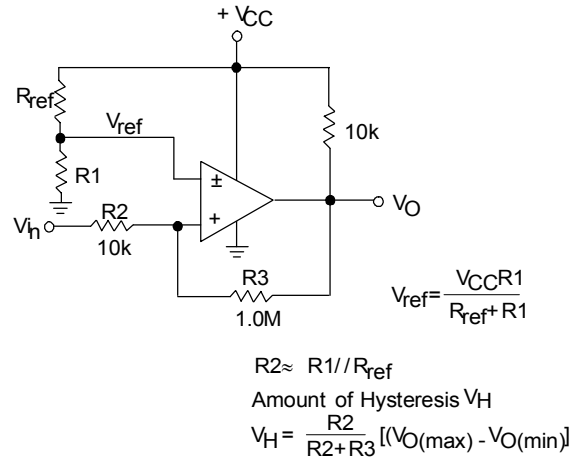
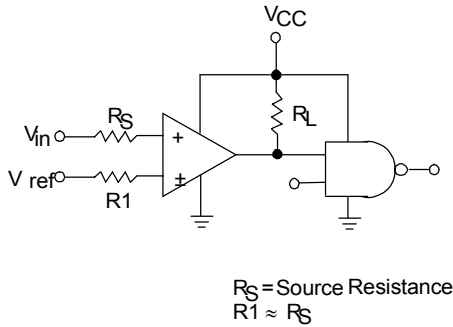


Figure 5. Noninverting Comparator with Hysteresis



Logic	Device	VCC (V)	RL kΩ
CMOS	1/4 MC14001	+15	100
TTL	1/4 MC7400	+5.0	10

Figure 6. Driving Logic

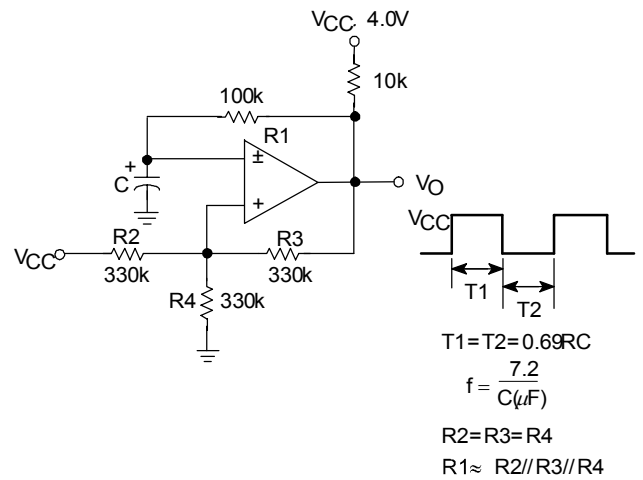


Figure 7. Squarewave Oscillator

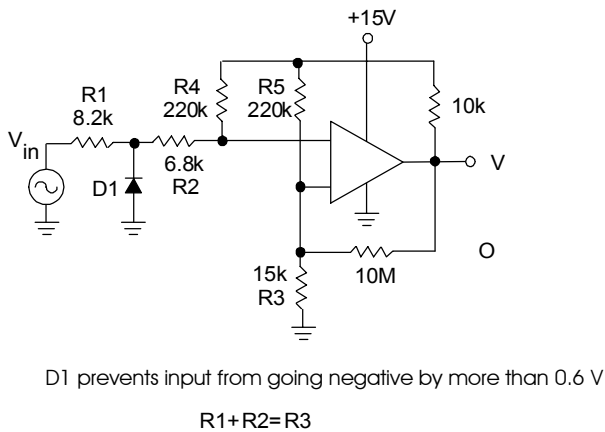


Figure 8. Zero Crossing Detector (Single Supply)

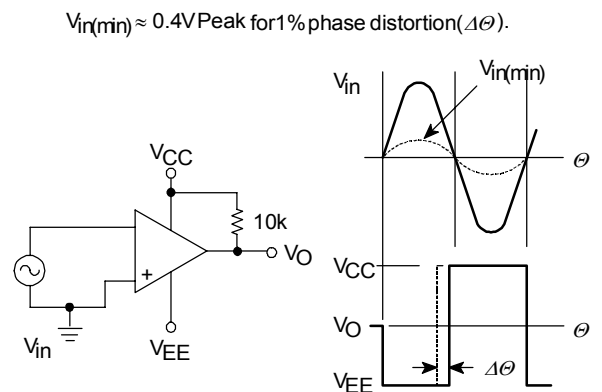


Figure 9. Zero Crossing Detector (Split Supplies)